

Material: TU872SLK					Single-Ended Impedance: 45 ohms		Single-Ended Impedance: 50 ohms		Differential Impedance: 82 ohms			Differential Impedance: 85 ohms			Differential Impedance: 90 ohms			Differential Impedance: 100 ohms			Differential Breakout		
Layer Name	Layer Description	Material	Required Thickness (mil)	Stackup Manufacturing	Layout Trace Characteristics (mil)	Impedance Target (ohms±%)	Layout Trace Characteristics (mil)	Impedance Target (ohms±%)	Layout Trace Characteristics		Impedance Target (ohms±%)	Layout Trace Characteristics		Impedance Target (ohms±%)	Layout Trace Characteristics		Impedance Target (ohms±%)	Layout Trace Characteristics		Impedance Target (ohms±%)	Final		Calculated Impedance (ohms)
				Copper Weight (Oz)					Width (mil)	Spacing (mil)		Width (mil)	Spacing (mil)		Width (mil)	Spacing (mil)		Width (mil)	Spacing (mil)				
	SOLDER MASK	Solder Mask	0.50																				
Signal1	SIGNAL	Copper	2.00	0.5 + 1 (plating)	7.7	45±10%	6.3	50±10%	6.32	4.9	82±10%	6	5.1	85±10%	5.25	5.25	90±10%	4.25	5.75	100±10%			
GPlane2	PREPREG	Low loss FR4	3.60																				
	GND	Copper	1.20	1.0																			
	CORE	Low loss FR4	4.00																				
Signal3	SIGNAL	Copper	1.20	1.0	4.65	45±10%	3.75	50±10%	4.5	3.9	82±10%	4.2	4.25	85±10%	3.52	3.9	90±10%	3.5	8.2	100±10%	3	4	95.5
GPlane4	PREPREG	Low loss FR4	4.50																				
	GND	Copper	1.20	1.0																			
	CORE	Low loss FR4	4.00																				
Signal5	SIGNAL	Copper	1.20	1.0	4.65	45±10%	3.75	50±10%	4.5	3.9	82±10%	4.2	4.25	85±10%	3.52	3.9	90±10%	3.5	8.2	100±10%	3	4	95.5
GPlane6	PREPREG	Low loss FR4	4.50																				
	GND	Copper	1.20	1.0																			
	CORE	Low loss FR4	4.00																				
Signal7	SIGNAL	Copper	1.20	1.0	4.65	45±10%	3.75	50±10%	4.5	3.9	82±10%	4.2	4.25	85±10%	3.52	3.9	90±10%	3.5	8.2	100±10%	3	4	95.5
GPlane8	PREPREG	Low loss FR4	4.50																				
	GND	Copper	1.20	1.0																			
	CORE	Low loss FR4	4.00																				
Signal9	SIGNAL	Copper	1.20	1.0	4.65	45±10%	3.75	50±10%	4.5	3.9	82±10%	4.2	4.25	85±10%	3.52	3.9	90±10%	3.5	8.2	100±10%	3	4	95.5
GPlane10	PREPREG	Low loss FR4	4.50																				
	GND	Copper	1.20	1.0																			
	CORE	Low loss FR4	4.00																				
PPlane11	PWR	Copper	2.50	2.0																			
PPlane12	PREPREG	Low loss FR4	7.00																				
	PWR	Copper	2.50	2.0																			
	CORE	Low loss FR4	4.00																				
GPlane13	GND	Copper	1.20	1.0																			
	PREPREG	Low loss FR4	4.50																				
Signal14	SIGNAL	Copper	1.20	1.0	4.65	45±10%	3.75	50±10%	4.5	3.9	82±10%	4.2	4.25	85±10%	3.52	3.9	90±10%	3.5	8.2	100±10%	3	4	95.5
GPlane15	CORE	Low loss FR4	4.00																				
	GND	Copper	1.20	1.0																			
	PREPREG	Low loss FR4	4.50																				
Signal16	SIGNAL	Copper	1.20	1.0	4.65	45±10%	3.75	50±10%	4.5	3.9	82±10%	4.2	4.25	85±10%	3.52	3.9	90±10%	3.5	8.2	100±10%	3	4	95.5
GPlane17	CORE	Low loss FR4	4.00																				
	GND	Copper	1.20	1.0																			
	PREPREG	Low loss FR4	4.50																				
Signal18	SIGNAL	Copper	1.20	1.0	4.65	45±10%	3.75	50±10%	4.5	3.9	82±10%	4.2	4.25	85±10%	3.52	3.9	90±10%	3.5	8.2	100±10%	3	4	95.5
GPlane19	CORE	Low loss FR4	4.00																				
	GND	Copper	1.20	1.0																			
	PREPREG	Low loss FR4	4.50																				
Signal20	SIGNAL	Copper	1.20	1.0	4.65	45±10%	3.75	50±10%	4.5	3.9	82±10%	4.2	4.25	85±10%	3.52	3.9	90±10%	3.5	8.2	100±10%	3	4	95.5
GPlane21	CORE	Low loss FR4	4.00																				
	GND	Copper	1.20	1.0																			
	PREPREG	Low loss FR4	3.60																				
Signal22	SIGNAL	Copper	2.00	0.5 + 1 (plating)	7.7	45±10%	6.3	50±10%	6.32	4.9	82±10%	6	5.1	85±10%	5.25	5.25	90±10%	4.25	5.75	100±10%			
	SOLDER MASK	Solder Mask	0.50																				
Nominal Thickness			121.80	Tolerance: +/-10%																			